

MicroTCA MICROSLIM BACKPLANES



FEATURES

- Complies to MicroTCA.0 Specification Rev 1.0
- Star and Dual Star Topology options
- Optimized via signal integrity studies
- Compression-mount connectors for improved performance, reliability and field replacement capability

BOARD SPECIFICATIONS

- 20-layer board (1U), 24-layer board (3U)
- 2 oz. copper power and ground
- PCB UL listed 94V-0
- PCB FR-4 or equivalent
- PCB .195" thick

MECHANICAL SPECIFICATIONS

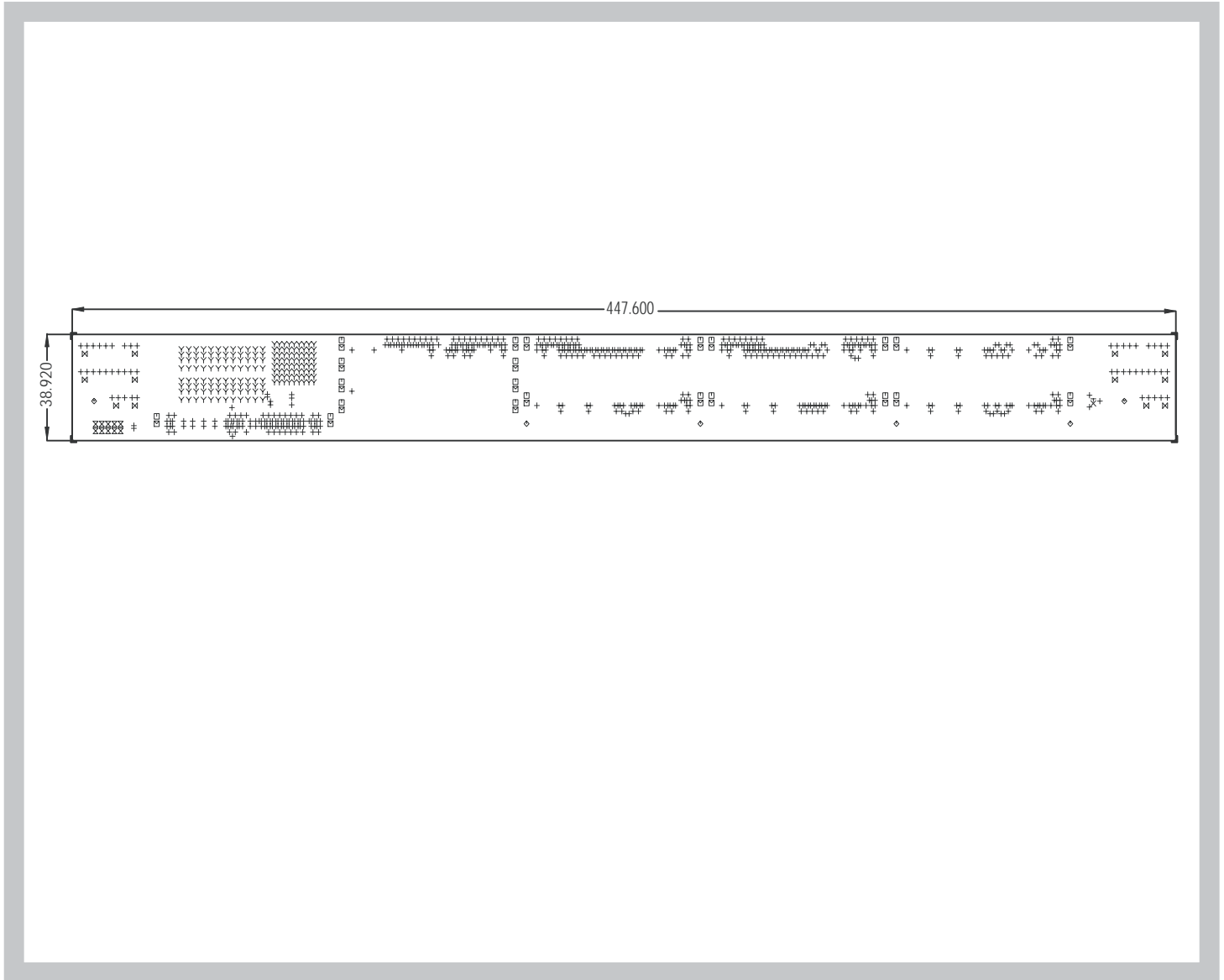
- 1U, 3U heights
- Full size modules
- Compression connectors

DESCRIPTION

The Bustronic MicroSlim backplanes come in sizes for 1U and 3U high chassis. The 1U features slots for 6 AMC, 1 PM (Power Module), 1 MCH (MicroTCA Carrier Hub), 1 JSM (J-TAG Switch Module) and 2 CUs (Cooling Units). The 3U features 12 AMC, 4HDD (with SATA), 2 PM, 2 MCH, 1 JSM, 3 spare slots, and 2 CUs. Compression-mount connectors are used in the backplanes for increased reliability and superior (easier and more flexible) routing. If a connector is damaged in the field, it has two screws securing it in place that can be easily removed for replacing the connector. The 1U backplane features Star routing for most of the signals and point-to-point connections for the PCI Express signals. The backplanes have undergone signal integrity studies to optimize the performance.

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LINE DRAWING



ORDER INFORMATION

Height	Slots	Description	Part Number
1U	9	6 AMC, 1 PM, 1 JSM, 1 MCH and 2 CUs (Cooling Units)	1900001880-0000R
3U	24	12 AMC, 4 HDD (w/SATA), 2 PM, 2 MCH, 1 JSM, 3 spare slots and 2 CUs (Cooling Units)	1900001881-0000R

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BACKPLANE MAPPING FOR MICROSLIM CHASSIS

